

Title (en)

SOLDER ALLOYS AND METHOD FOR THE REPAIR OF A COMPONENT

Title (de)

LOTLEGIERUNGEN UND VERFAHREN ZUR REPARATUR EINES BAUTEILS

Title (fr)

ALLIAGES DE BRASAGE ET DISPOSITIF POUR LA RÉPARATION D'UN ÉLÉMENT DE CONSTRUCTION

Publication

EP 2117766 A1 20091118 (DE)

Application

EP 08709220 A 20080226

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- EP 07011676 A 20070614
- EP 08709220 A 20080226

Abstract (en)

[origin: WO2008110454A1] Many known solder alloys according to prior art utilize silicon or boron as melting point reducers, which, however, form brittle phases that have an undesirable effect on the thermo-mechanical properties. The solder alloy comprises gallium and/or germanium, preferably forming the 'Y' phase and having improved mechanical properties.

IPC 8 full level

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CPC (source: EP KR US)

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Citation (search report)

See references of WO 2008110454A1

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